

fully automatic

Automation level

manual

> 1

Bonds/day

100.000

53
SERIES



56
SERIES



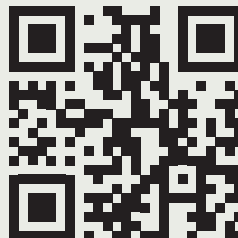
58
SERIES



TECHNOLOGY	SERIES 53	SERIES 56	SERIES 58
GOLD-BALL	5310, 53xx BDA	5610	5810
THIN WIRE WEDGE-WEDGE	5330	5630	5830
THIN WIRE DEEP ACCESS	53xx BDA	5632	5832
HEAVY WIRE	5350	5650	5850
HEAVY RIBBON	5350 HR	5650 HR	5850 HR
BONDTESTER	---	5600/5600C	---

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BONDING THE STARS

F&S
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SERIES 56

FLEXIBLE.

AUTOMATIC.

UNIQUE.



56
SERIES

BONDING THE STARS

FAS
BONDTEC

SERIES 56

Desktop Micro Factory

YOU NEED: **1.000 to 10.000 WIREBONDS PER DAY**

- >> In-house production to protect your technology and to provide short Time-to-Market
- >> High Mix / Medium Volume; frequent product changes at medium lot sizes
- >> Fully automatic production with perfect wirebond quality
- >> Extendable to a fully automatic bondtester
- >> All wirebonding technologies on one basic machine



THE SOLUTION: **SERIES 56**

- >> Unbeatable flexibility
- >> Changeable bondheads for all wirebond and testing process
- >> Fully automatic bonding with manual part feeding
- >> Store an unlimited number of bond programs
- >> Extremely adaptable bond settings, loop shapes, force and power profiles etc.
- >> Most powerful pattern recognition system on the market
- >> Innovative and intuitiv programmable software
- >> 6 in 1

56
SERIES

EXCHANGEABLE BOND HEADS



5610 – Gold-Ball



- >> Gold-ball bonding for wires from 17.5 to 50 μm using standard capillaries 16 mm to 19 mm controlled, programmable bond force for delicate component surfaces
- >> Digital ultrasonic generator provides adjustable bond frequencies
- >> Bumping, safety bump, stitch-on-ball



5630 – Wedge-Wedge



- >> Wedge-wedge bonding using 1" tools for aluminum and Goldwires from 17,5 to 75 μm strength
- >> 45° wire guide, convertible to 30° or 60° depending on component geometry
- >> Digital ultrasonic generator provides adjustable bond frequencies
- >> Deformation Limit Control (DLC) for quality control



5632 – Deep Access



- >> Wedge-Wedge-bonding using 1" oder ¾" Tools
- >> 90° wire guide for aluminum and gold wires from 17.5 to 75 μm
- >> Perfect for difficult and constricted bonding geometries
- >> Ideally suited for aluminum and gold ribbons
- >> Deformation Limit Control (DLC) for real-time quality check and process monitoring



5650 – Dickdraht



- >> Wedge-wedge bonding for aluminum and copper heavy wire from 100 up to 500 μm diameter
- >> Wedge lengths of 50 up to 70 mm even for extreme bonding requirements
- >> Stitch or chain bonds of any length
- >> Clip-on wire guide for quick exchange
- >> Deformation Limit Control (DLC) for quality control

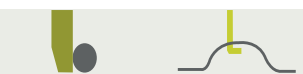
5650 HR– Heavy Ribbon



- >> Wedge-wedge bonding for heavy aluminum or copper ribbons up to 2 mm width
- >> Increased programmable bond force up to 6,000 cN, also with force and power ramps
- >> Active ribbon guide to improve loop shaping



5600 – Pull- & Sheartester



- >> Manual testing of thin- and heavy wire bonds
- >> Easily changable cartridges

5600C – Automatic Pull- & Sheartester

- >> Test heads with changeable cartridges
- >> Camerasystem for automatic testing
- >> Analysis software